

## Overview

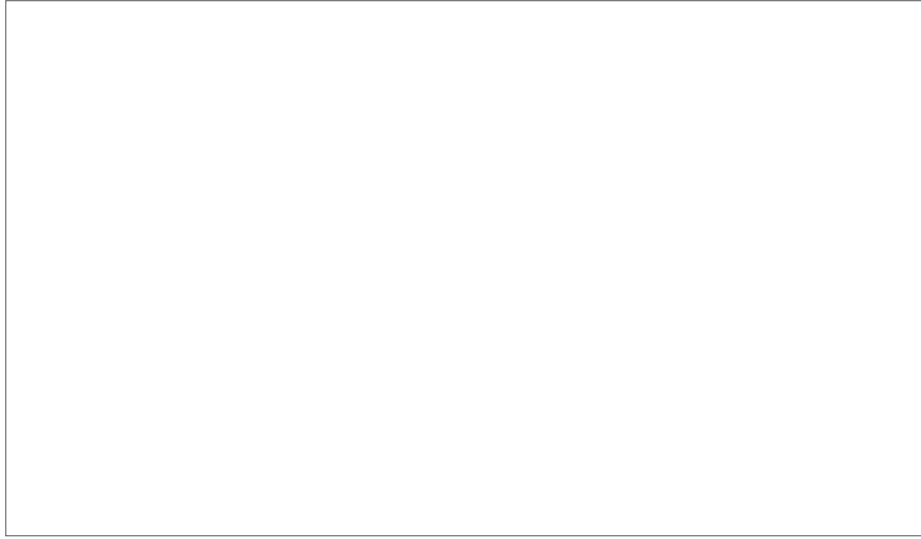
## Benefits





## Defect Analysis

## Interactive Lot, Wafer and Defect Extraction Reports



## Binsort E-Test-Defect Correlation

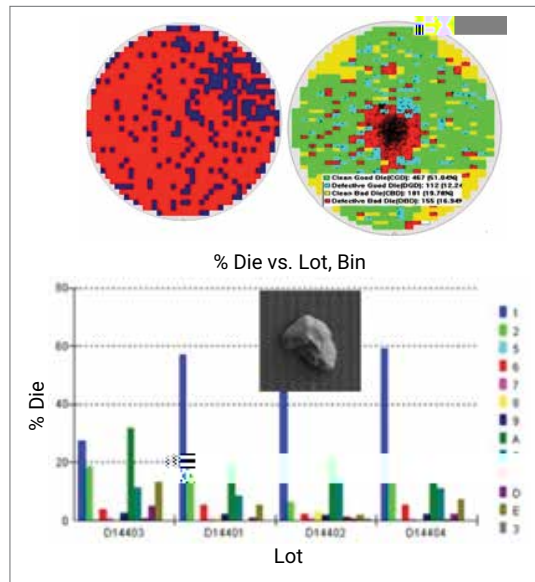


Figure 5: Defect to binsort correlation improves yield monitoring

## Enhanced Bitmapping

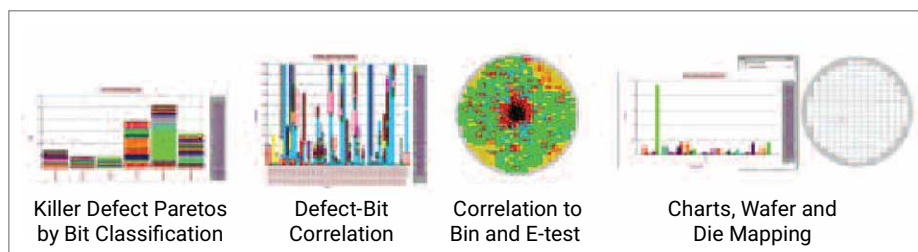


Figure 6: Comprehensive defect bitmap and sort correlation analysis to improve yield monitoring

## MES/WIP Analysis

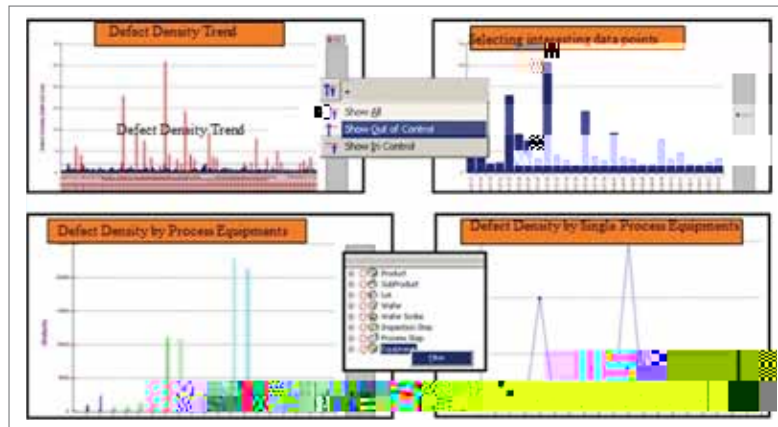


Figure 7: Typical MES systems include PROMIS™, FACTORYworks™, WorkStream™ and Siview™

## Parametric Module

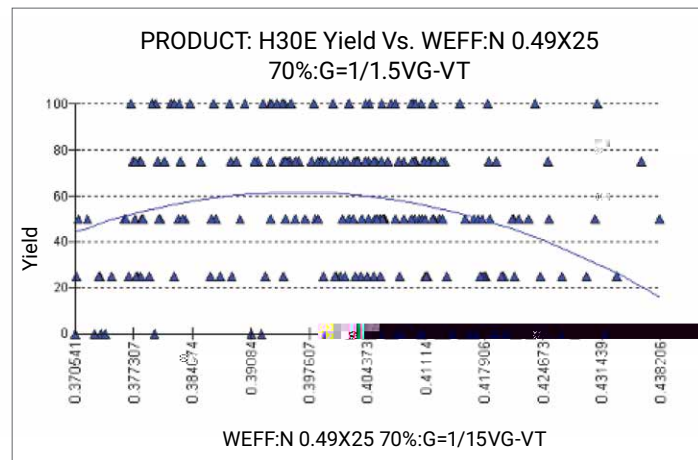


Figure 8: Parametric module imports inline and EOL device performance structures for correlation to die fallout across a wafer or group of wafers

